UNITED STATES PATENT AND TRADEMARK OFFICE

UNITED STATES DEPARTMENT OF COMMERCE
United States Patent and Trademark Office
Address: COMMISSIONER FOR PATENTS
P.O. Box 1450
Alexandria, Virginia 22313-1450
www.uspto.gov

APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
10/617,578	07/11/2003	Steven P. Nally	108298533US1	3549

25096 7590 03/01/2006

PERKINS COIE LLP
PATENT-SEA
P.O. BOX 1247
SEATTLE, WA 98111-1247

EXAMINER	
ALANKO, ANITA KAREN	
ART UNIT	**PAPER NUMBER**
1765	

DATE MAILED: 03/01/2006

Please find below and/or attached an Office communication concerning this application or proceeding.

6

UNITED STATES DEPARTMENT OF COMMERCE
U.S. Patent and Trademark Office
Address: COMMISSIONER FOR PATENTS
P.O. Box 1450
Alexandria, Virginia 22313-1450

APPLICATION NO./ CONTROL NO.	FILING DATE	FIRST NAMED INVENTOR / PATENT IN REEXAMINATION	ATTORNEY DOCKET NO.
10/617,578	7/11/03	Nally	10829853 3USI

EXAMINER

ART UNIT	PAPER
	022406

DATE MAILED:

Please find below and/or attached an Office communication concerning this application or proceeding.

Commissioner for Patents

Attached please find an English translation for KR 97-008549. Applicant is requested to consider this in the response to the outstanding office action mailed 2/13/06.

Anita K. Alanko

Anita K Alanko
Primary Examiner
Art Unit: 1765

PTO-90C (Rev.04-03)

MARKING REMOVAL DEVICE FOR SEMICONDUCTOR CHIP PACKAGE AND MARKING REMOVAL METHOD USING THE DEVICE

Dong Wan Kye, et al.

UNITED STATES PATENT AND TRADEMARK OFFICE
WASHINGTON, D.C. FEBRUARY 2006
TRANSLATED BY THE MCELROY TRANSLATION COMPANY

KOREAN INTELLECTUAL PROPERTY OFFICE (KR)
PATENT JOURNAL (A)
KOREAN PATENT APPLICATION TEUK 1997-0008549

Int. Cl.[6]:	H 01 L 23/544
Filing No.:	Teuk 1995-0022124
Filing Date:	July 25,1995
Publication Date:	February 24,1997
Examination request:	Filed

MARKING REMOVAL DEVICE FOR SEMICONDUCTOR CHIP PACKAGE AND MARKING REMOVAL METHOD USING THE DEVICE

[Ban-do-che chip pa-ki-ji-ui ma-king je-ku-jang-chi mit keu-reul yee-yong-han ma-king je-ku-bang-bub]

Inventors:	Dong Wan Kye et al.
Applicant:	Samsung Electronics Company

Representative figure

Figure 1

Brief description of the figure

Figure 1 is a diagram showing the marking removal method for semiconductor chip packages of the present invention. Figure 2 is a plan view of a window plate having various pad windows that are used in the marking removing method for semiconductor chip packages of the present invention.

The contents are presented to publish the principal parts and therefore the entire content is not recorded.

Claims

1. Marking removal device for semiconductor chip packages, wherein the device that removes the markings of semiconductor chip packages is equipped with a support section that is extended so that it does not physically contact external leads built into the semiconductor chip package; a window pad formed to expose the marking area of the semiconductor chip package supported by the support section; a window plate that has at least one or more of the aforementioned window pads formed.

2. Marking removal device for semiconductor chip packages of Claim 1, characterized by being surrounded by rubber to prevent static electricity in a certain area of the aforementioned support section.

3. Marking removal device for semiconductor chip packages of Claim 1, wherein the aforementioned support section extends higher than the height of the aforementioned external lead.

4. Marking removal device for semiconductor chip packages of Claim 1, wherein the aforementioned window pad is formed no larger than the semiconductor chip package, when comparing to the size of the aforementioned semiconductor chip package.

5. Marking removal method using a marking removal device for semiconductor chip packages, which includes a step wherein the opposite side of the package markings is pushed into a certain area of the support section of the marking removal device; and a step wherein the markings on the marked face of the package in contact with the device is removed by a chemical removal agent.

6. Marking removal method using the marking removal device for semiconductor chip packages of Claim 5, wherein the aforementioned chemical removal agent is in liquid phase or vapor phase.

7. Marking removal method using the marking removal device for semiconductor chip packages of Claim 5, characterized in that the aforementioned marking removal method using the aforementioned chemical removal agent is a reflow, dipping and spray method.

8. Marking removal method using the marking removal device for semiconductor chip package of Claim 5, characterized by an additional rinse step so as to eliminate the residues of the markings removed by the aforementioned chemical removal agent.

9. Marking removal method using the marking removal device for semiconductor chip package of Claim 8, characterized in that the rinsing agent used in the aforementioned rinse step is distilled water.

Note: Published from contents of the first application.

Figure

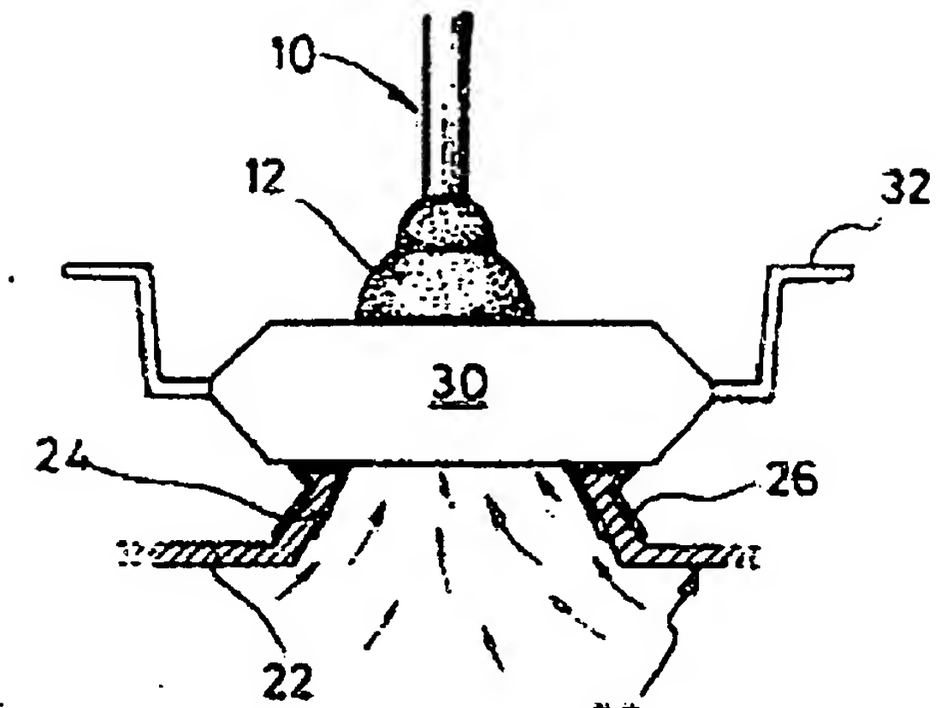

Figure 1

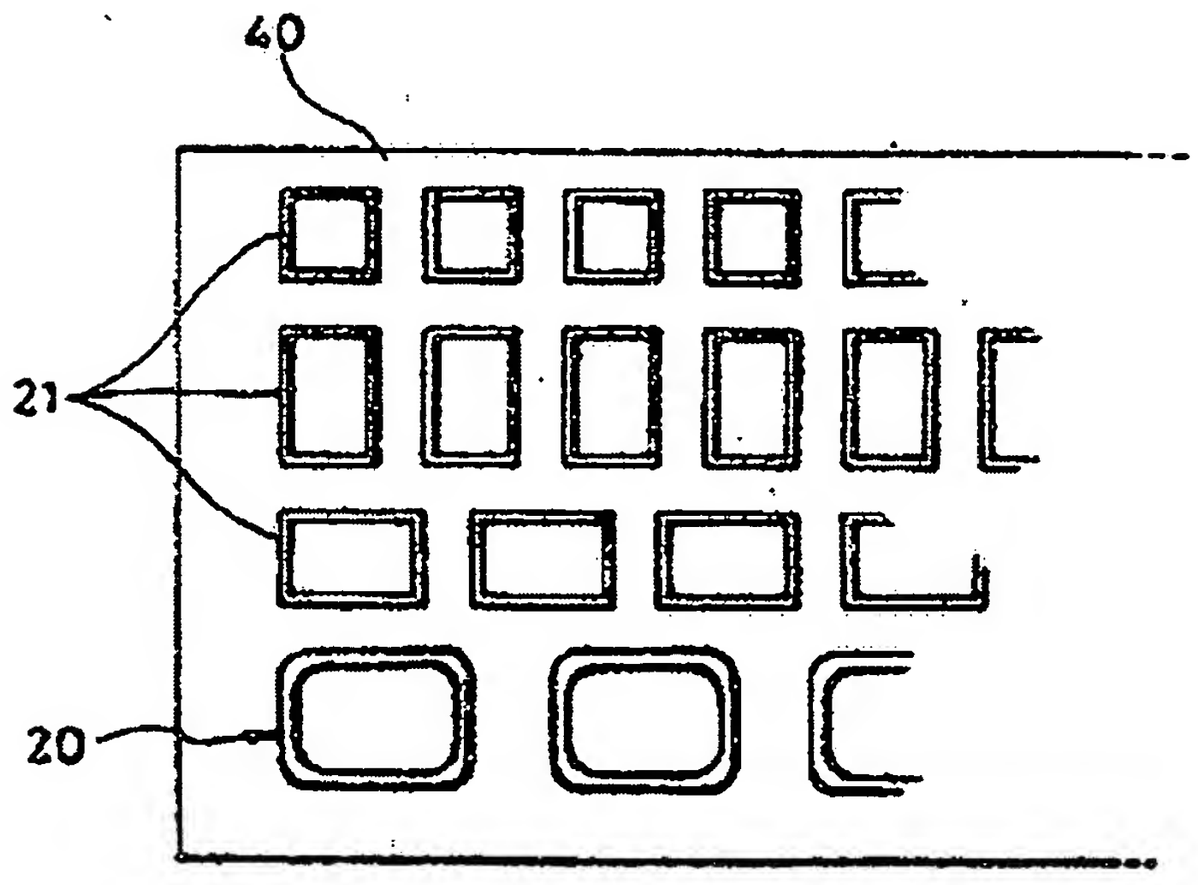

Figure 2